

# SOT399

plastic single-ended through-hole package; mountable to heatsink; 1 mounting hole; 3 in-line leads

8 February 2016

Package information

## 1. Package summary

|                                       |                                 |
|---------------------------------------|---------------------------------|
| <b>Terminal position code</b>         | S (single)                      |
| <b>Package type descriptive code</b>  | TOP-3D                          |
| <b>Package type industry code</b>     | TOP-3D                          |
| <b>Package style descriptive code</b> | SFM (single-ended flange mount) |
| <b>Package style suffix code</b>      | NA (not applicable)             |
| <b>Package body material type</b>     | P (plastic)                     |
| <b>Mounting method type</b>           | H (heatsink mount)              |
| <b>Issue date</b>                     | 6-11-1998                       |

Table 1. Package summary

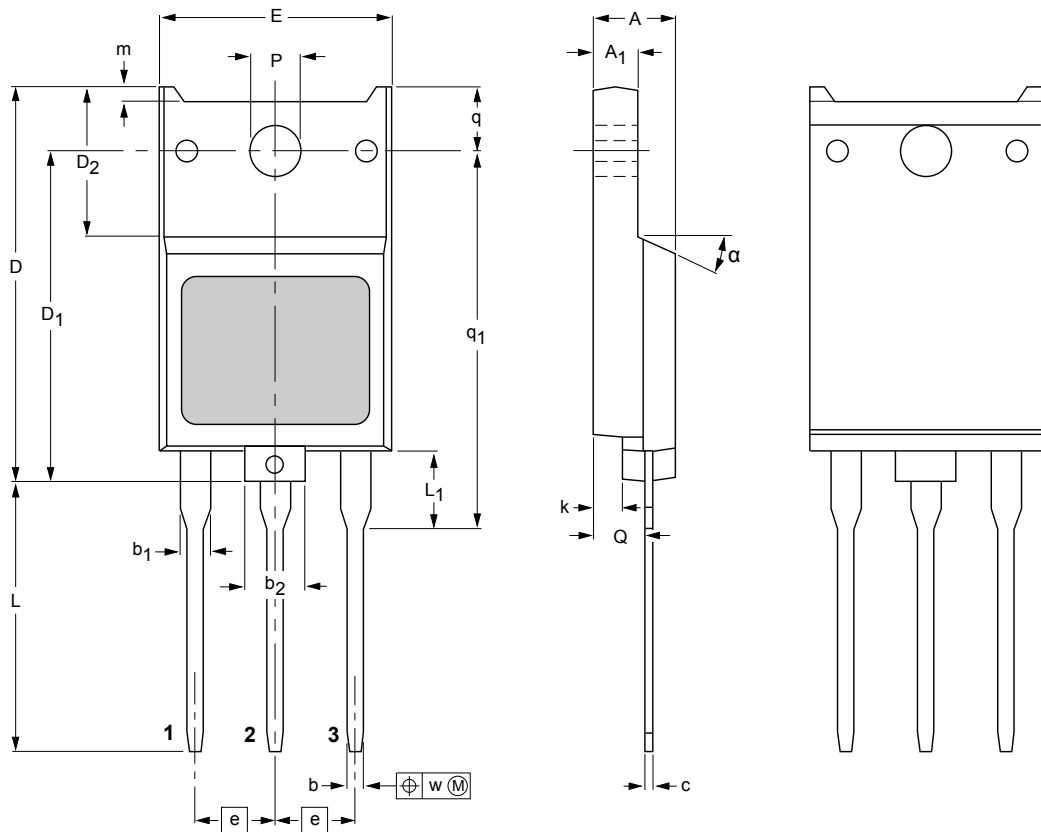
| Symbol         | Parameter                      | Min | Typ | Nom  | Max | Unit |
|----------------|--------------------------------|-----|-----|------|-----|------|
| D              | package length                 | 26  | -   | 26.5 | 27  | mm   |
| E              | package width                  | 15  | -   | 15.5 | 16  | mm   |
| A              | seated height                  | 4.8 | -   | 5.3  | 5.8 | mm   |
| e              | nominal pitch                  | -   | -   | 2.54 | -   | mm   |
| n <sub>2</sub> | actual quantity of termination | -   | -   | 3    | -   |      |



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## 2. Package outline

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DIMENSIONS (mm are the original dimensions)

| UNIT | A          | A <sub>1</sub> | b          | b <sub>1</sub> | b <sub>2</sub> | c          | D        | D <sub>1</sub> | D <sub>2</sub> | E        | e    | k          | L            | L <sub>1</sub> <sup>(1)</sup> | m          | P          | Q          | q          | q <sub>1</sub> | w   | α          |
|------|------------|----------------|------------|----------------|----------------|------------|----------|----------------|----------------|----------|------|------------|--------------|-------------------------------|------------|------------|------------|------------|----------------|-----|------------|
| mm   | 5.8<br>4.8 | 3.3<br>2.7     | 1.2<br>0.9 | 2.2<br>1.8     | 4.7<br>4.2     | 0.9<br>0.6 | 27<br>26 | 22.5<br>21.5   | 10.2<br>9.9    | 16<br>15 | 5.45 | 2.2<br>1.8 | 19.1<br>18.1 | 5.4<br>4.8                    | 0.8<br>0.6 | 3.4<br>3.1 | 3.4<br>3.2 | 4.7<br>4.3 | 25.7<br>25.1   | 0.4 | 27°<br>23° |

**Note**

1. Tinning of terminals are uncontrolled within zone L<sub>1</sub>.

| OUTLINE VERSION | REFERENCES |       |      | EUROPEAN PROJECTION | ISSUE DATE |
|-----------------|------------|-------|------|---------------------|------------|
|                 | IEC        | JEDEC | EIAJ |                     |            |
| SOT399          |            |       |      |                     | 98-11-06   |

Fig. 1. Package outline TOP-3D (SOT399)

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### 3. Legal information

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